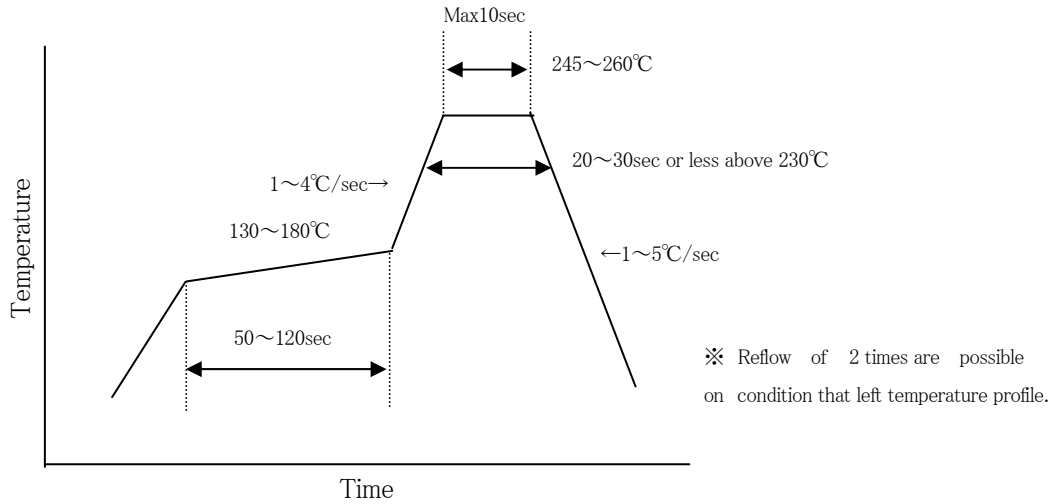


Corresponding Pb-Free Mounting Method

【Reflow Method】

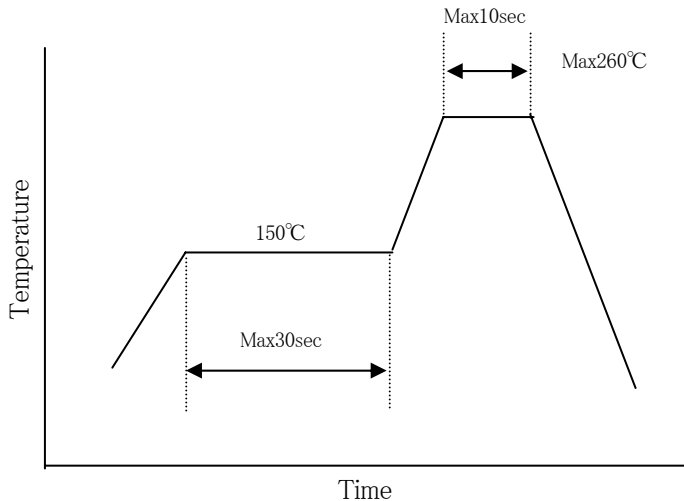
SC-59,SC-74,SC-70,SC-75A,USM6F,SC-88,SC-88A,SOT-89,SC-63 Package
(TO-92S Package products is not recommended to reflow method.)



It recommends to have the peak temperature of equal to more than 245°C to secure Solder wet ability.

【Flow Method】

SC-59,SC-74,SC-70,SC-75A,SC-88,SC-88A,SOT-89,SC-63,TO-92S Package
(USM6F Package products is not recommended to flow method.)



※Flow is within the limits only part of lead.
※Flow of 2 times are possible on condition that left temperature profile.

Fix devices on a substrate with an adhesive agent and dip the substrate into molten solder. When the molten solder has a low melting point, The following conditions are recommended:

- Solder Temperature 260°C
- Flow Time 10sec

When you use a large substrate, preheat the substrate at temperature 150°C for 20 to 30 second, because the substrate may not reach to required temperature within the flow time above due to the large thermal capacity.

It recommends to have the peak temperature of equal to more than 245 °C to secure Solder wet ability.

【Hands Dipping Method】

Please be careful to use time and temperature on condition that
Solder temperature : more less 380°C dipping time to 3sec.